

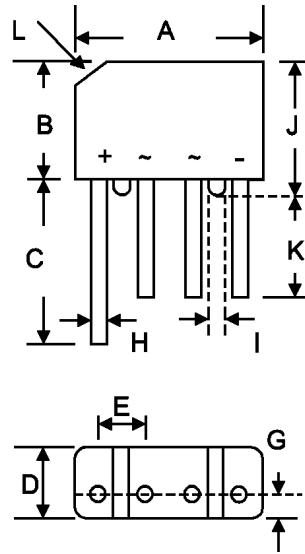
### 2.0A GLASS PASSIVATED BRIDGE RECTIFIER

#### FEATURES

- \* Glass Passivated Die Construction
- \* Typical  $I_R$  less than 0.1uA
- \* High case dielectric strength
- \* Ideal for printed circuit boards
- \* High Surge Current Capability
- \* High temperature soldering guaranteed:  
260 /10 second at 5 lbs (2.3kg) tension.

#### MECHANICAL DATA

- \* Case: Molded Plastic
- \* Epoxy: UL94V-O rate flame retardant
- \* Terminals : Plated Leads Solderable  
Per MIL-STD-750 Method 2026
- \* Polarity : As Marking on Body
- \* Mounting Position: Any
- \* Weight : 1.7 gram (approx.)
- \* Marking:Type Number



KBP		
Dim	Min	Max
A	14.22	15.24
B	10.66	16.68
C	15.20	---
D	4.56	5.10
E	3.60	4.30
G	2.16	2.54
H	0.76	0.85
I	1.52	---
J	11.68	12.70
K	12.70	---
L	3.2×45° Typical	
Unit :mm		

### MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

- \* Rating at 25 ambient temperature unless otherwise specified
- \* Single phase, half wave. 60Hz, resistive or inductive load.
- \* For capacitive load derate current by 20 %

Characteristic	Symbol	2KBP 005M	2KBP 01M	2KBP 02M	2KBP 04M	2KBP 06M	2KBP 08M	2KBP 10M	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	$V_{RRM}$ $V_{RWM}$ $V_R$	50	100	200	400	600	800	1000	V
RMS Reverse Voltage	$V_{R(RMS)}$	35	70	140	280	420	560	700	V
Average Rectifier Forward Current (Note 1) @ $T_A=55$	$I_{O(AV)}$	2.0							A
Non-Repetitive Peak Surge Current 8.3 ms Single half sine-wave superimposed on rated load ( JEDEC Method)	$I_{FSM}$	60							A
Forward Voltage (per element) ( $I_F = 2.0$ Amp)	$V_{FM}$	1.1							V
Peak Reverse Current ( Rated DC Voltage, $T_C = 25$ ) ( Rated DC Voltage, $T_C = 100$ )	$I_R$	5.0 500							uA
Rating for Fusing( $t < 8.3$ ms)	$I^2t$	15							A <sup>2</sup> s
Typical Junction Capacitance per element (Note2)	$C_J$	25							pF
Typical Thermal Resistance (note 3)	$R_{\theta JA}$	30							k/W
Operating and Storage Temperature Range	$T_J, T_{stg}$	-65 to +165							

Note: 1 Lead maintained at ambient temperature at a distance of 9.5 mm from the case.

2. Measured at 1.0 MHz and applied reverse voltage of 4.0V D.C.

3. Thermal resistance junction to ambient, mounted on PC board with 12 mm<sup>2</sup> copper pad.

# 2KBP005M Thru 2KBP10M

FIG-1 FORWARD CURRENT DERATING CURVE

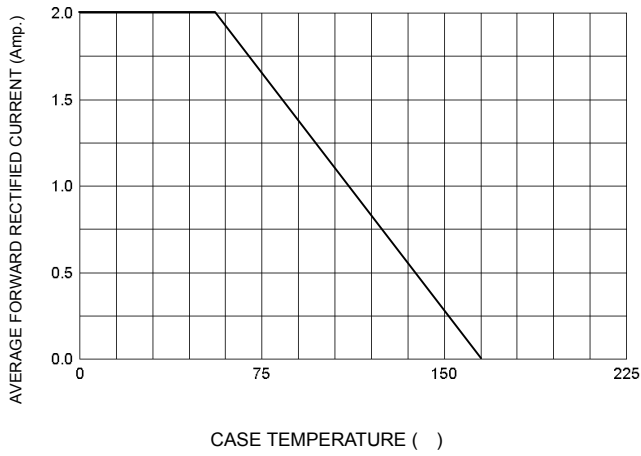


FIG-2 TYPICAL FORWARD CHARACTERISTICS

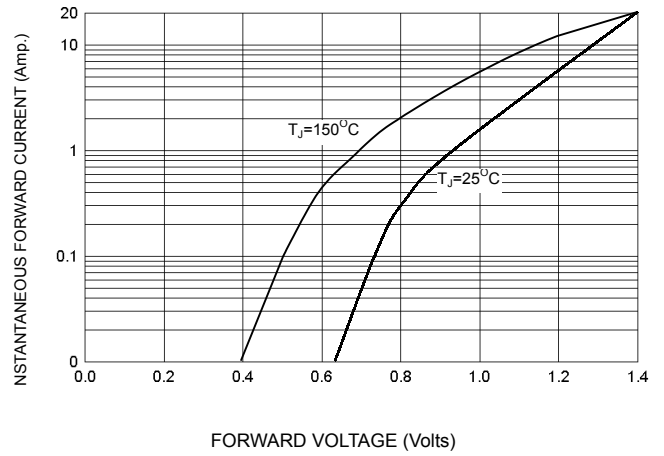


FIG-3 PEAK FORWARD SURGE CURRENT

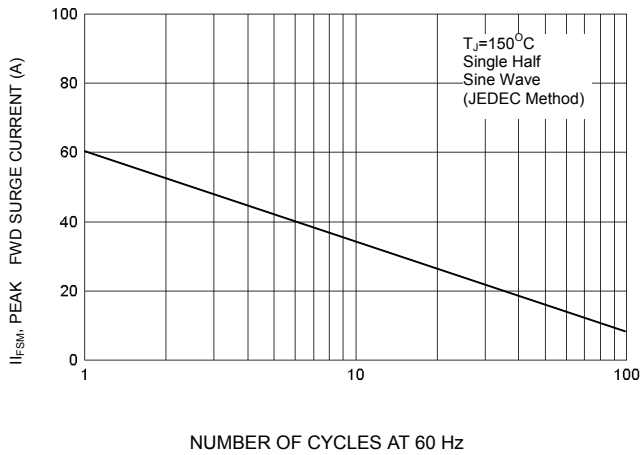


FIG-4 TYPICAL JUNCTION CAPACITANCE

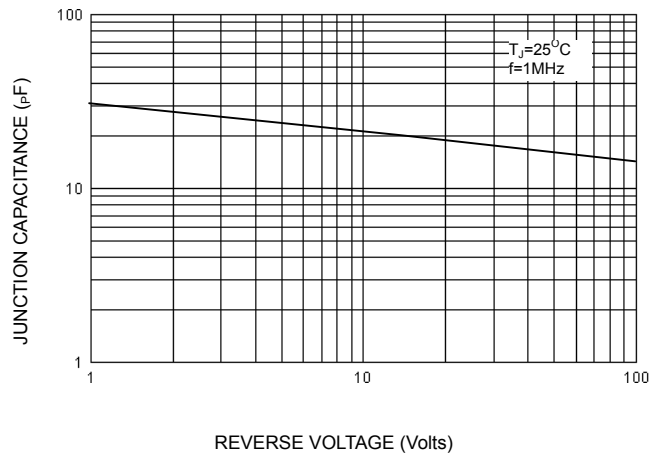


FIG-5 TYPICAL REVERSE CHARACTERISTICS

